An apparatus for exhausting coating materials used in the process of spin coating a top surface of a wafer, the wafer having an edge and a bottom surface that is supported and rotated by a rotatable chuck attached by a shaft to a spin motor. The apparatus includes a bowl having an exhausted drain configured to receive excess liquid and vapor from the spin coating and an assembly configured to maintain the drain at a negative pressure differential relative to the bowl. In a preferred embodiment, a baffle is attached to the bottom to limit the flow of the liquid and vapor into the drain to a predetermined direction.

9 Claims, 8 Drawing Sheets